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To the deposition of the Ti film generally consumes approximately 10% of the $TiCl_4$ gas, and the remaining gas (about 90%) as a non-reaction gas and reaction by-products of $TiCl_2$, $TiCl_3$ and HCl are fed into the exhaust pipe 30 from the exhaust ports 28 together with the exhaust gas by the vacuum pump 33. The exhaust gas further flows down in the order of the trap mechanism 32, the vacuum pump 33 and the eliminator 34. In this case, the non-reacting $TiCl_4$ gas, and the reaction by-products, have a relatively high vapor pressure, which are not generally possible to be sufficiently removed by the trap mechanism 32.

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Please replace the paragraph at page 25, lines 8-21, as follows:

Second exhaust valves 150A, 150B are provided between the nozzle 162 and the upstream flange joint 146, and the downstream flange joint 148 and the vacuum pump 134 respectively. An exhaust bypass pipe 152 having a bypass valve 154 disposed therein is provided to communicate the bypass exhaust port 124 of the process container 106 with the portion 130A or the exhaust pipe 130 directly downstream of the second exhaust valve 150B. The inner diameter of the exhaust bypass pipe 152 is, for example, 20 mm, significantly smaller than the inner diameter of the exhaust pipe 130 which carries out main exhaust. The process container 106 can be therefore evacuated with a large inverse diffusion coefficient as will be discussed later.

Please replace the paragraph at page 25, line 22 to page 26, line 15, as follows:

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Oxidative-gas feeding means 160 is connected to that portion of the exhaust pipe 130 which is located directly downstream of the first exhaust valve 140. Specifically, this oxidative-gas supply means 160 comprises a gas injection nozzle 162 whose distal end is inserted into the exhaust pipe 130 through the peripheral wall thereof, an oxidative gas pipe 164 connected to the nozzle 162, and an oxidative gas source 166. The gas injection nozzle 162 and the exhaust pipe 130 may be those illustrated in FIGS. 4A, 4B and 4C may be used. An oxidative gas valve 168 and a flow controller 179, which controls the flow rate of the

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